



Features

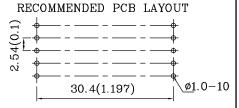
- Low power consumption
- ullet Robust package
- I.C. Compatible
- Standard configuration: Gray face w/ white

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- Optional black face provides superior color contrast
- RoHS Compliant

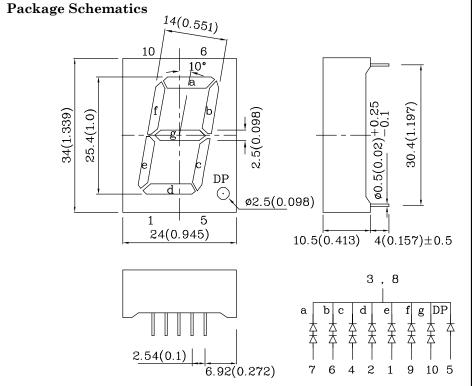








ATTENTION OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES



- 1. All dimensions are in millimeters (inches), Tolerance is \pm 0.25(0.01")unless otherwise noted.
- 2. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)	DGK (InGaN)	Unit		
Reverse Voltage (Per Chip)	$V_{\rm R}$	5	V	
Forward Current (Dp)	I_{F}	25 (25)	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width (Dp)	150 (150)	mA		
Power Dissipation (Per Chip)	P_D	102.5	mW	
Operating Temperature	$T_{\rm A}$	-40 ~ +85	°C	
Storage Temperature	Tstg	-40 ~ +85		
Electrostatic Discharge Threshol (HBM)	450	V		
Lead Solder Temperature [2mm Below Package Base]	260°C For 3~5 Seconds			

Operating Characteristics (T _A =25°C)		DGK (InGaN)	Unit
Forward Voltage (Typ.) (Dp) (I _F =10mA)	V_{F}	6 (3)	V
Forward Voltage (Max.) (Dp) (I _F =10mA)	V_{F}	8.2 (4.1)	V
Reverse Current (Max.) (Per Chip) (V _R =5V)	I_R	50	uA
Wavelength of Peak Emission CIE127-2007* (Typ.) $(I_F=10\text{mA})$	λР	515*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) $(I_F=10\text{mA})$	λD	525*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =10mA)	Δλ	35	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	45	pF

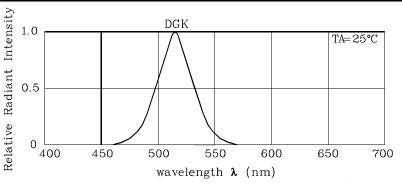
Part Number	Emitting Color	Emitting Material	Luminous Intensity CIE127-2007* (IF=10mA) ucd		Wavelength CIE127-2007* nm λP	Description
			min.	typ.		
XDDGK25C	Green	InGaN	255000 88000*	789990 259990*	515 *	Common Cathode, Rt.Hand Decimal

^{*}Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.

Jan 20,2014

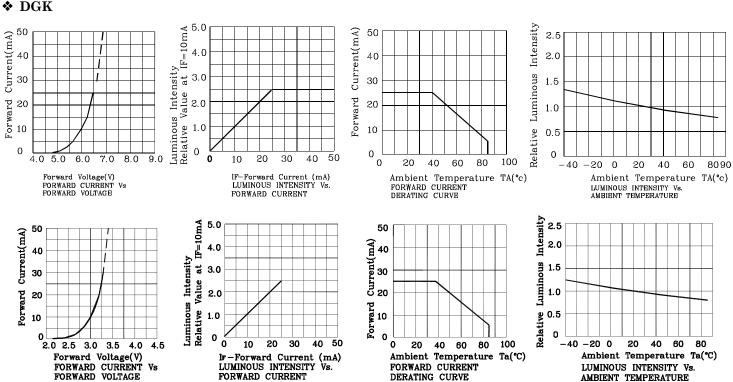
XDSB7711 V1-X Layout: Maggie L.



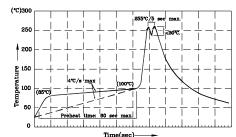


RELATIVE INTENSITY Vs. CIE WAVELENGTH

❖ DGK



Wave Soldering Profile for Thru-Hole Products (Pb-Free Components)



- 2.Peak wave soutering transformax).
 3.Do not apply stress to the epoxy resint.
 4.Fixtures should not incur stress on the during soldering process.
 5.SAC 305 solder alloy is recommended.
 6.No more than one wave soldering pass.

Remarks:

DERATING CURVE

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength),

the typical accuracy of the sorting process is as follows:

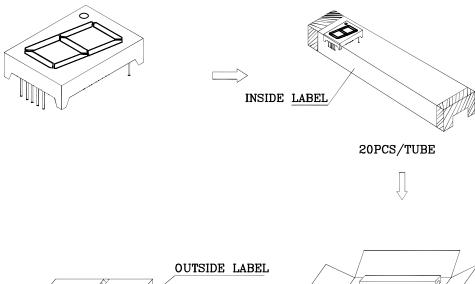
- 1. Wavelength: +/-1nm
- 2. Luminous Intensity / Luminous Flux: +/-15%
- 3. Forward Voltage: +/-0.1V

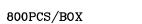
Note: Accuracy may depend on the sorting parameters.

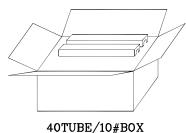
AMBIENT TEMPERATURE



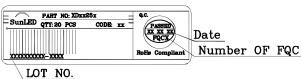
PACKING & LABEL SPECIFICATIONS



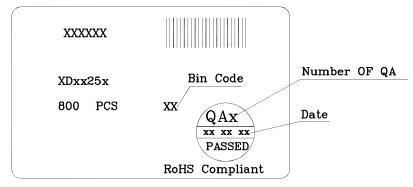




Inside Label On IC-tube



Outside Label On Box



TERMS OF USE

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- 2. Contents within this document are subject to improvement and enhancement changes without notice.
- 3. The product(s) in this document are designed to be operated within the electrical and environmental specifications indicated on the datasheet. User accepts full risk and responsibility when operating the product(s) beyond their intended specifications.
- 4. The product(s) described in this document are intended for electronic applications in which a person's life is not reliant upon the LED. Please consult with a SunLED representative for special applications where the LED may have a direct impact on a person's life.
- 5. The contents within this document may not be altered without prior consent by SunLED.
- $6. \ Additional\ technical\ notes\ are\ available\ at\ \underline{http://www.SunLEDusa.com/TechnicalNotes.asp}$

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